

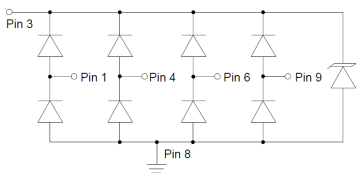
Description

The DL0534MP is an ultra low capacitance TVS array, utilizing leading monolithic silicon technology to provide fast response time and low ESD clamping voltage, making this device an ideal solution for protecting voltage sensitive high speed data lines. The DL0534MP has an ultra low capacitance with a typical value at 1.5pF, and complies with the IEC 61000-4-2 (ESD) standard with $\pm 30\text{kV}$ air and $\pm 30\text{kV}$ contact discharge. It is assembled into a 10-pin lead-free MSOP package. The flow through style package allows for easy PCB layout and matched trace lengths necessary to maintain consistent impedance between high speed differential lines. The small size, ultra low capacitance and high ESD surge protection make DL0534MP an ideal choice to protect high speed ports.

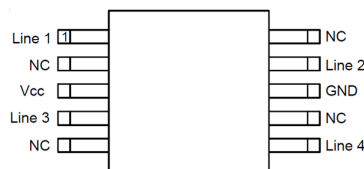
Mechanical Characteristics

- ◆ Package: MSOP-10
- ◆ Lead Finish: Matte Tin
- ◆ Case Material: "Green" Molding Compound.
- ◆ UL Flammability Classification Rating 94V-0
- ◆ Moisture Sensitivity: Level 3 per J-STD-020
- ◆ Terminal Connections: See Diagram Below
- ◆ Marking Information: See Below

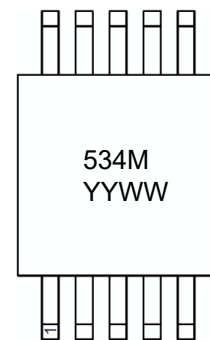
Dimensions and Pin Configuration



Circuit Diagram



Pin Schematic



534M = Device Marking Code
 YYWW = Date Code
 Dot denotes pin1

Features

- ◆ Ultra low capacitance: 1.5pF typical
- ◆ Ultra low leakage: nA level
- ◆ Low operating voltage: 5V
- ◆ Low clamping voltage
- ◆ Protects one power line and four data lines
- ◆ Flow-through package
- ◆ Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
 - Air discharge: $\pm 30\text{kV}$
 - Contact discharge: $\pm 30\text{kV}$
 - IEC61000-4-4 (EFT) 40A (5/50ns)
 - IEC61000-4-5 (Lightning) 12A (8/20 μs)
- ◆ RoHS Compliant

Applications

- ◆ DVI Ports
- ◆ HDMI Ports
- ◆ Set Top Box
- ◆ Projection TV
- ◆ Notebook Computers
- ◆ 10/100/1000 Ethernet
- ◆ Monitors and Flat Panel Displays

Marking Information

Ordering Information

Part Number	Marking	Packaging	Reel Size
DL0534MP	534M	3000/Tape & Reel	13 inch

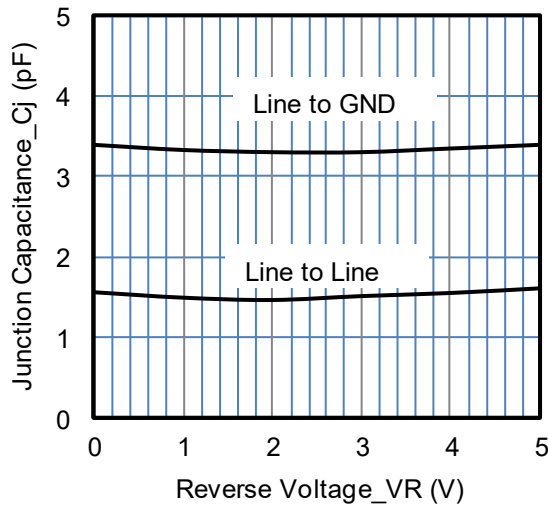
Absolute Maximum Ratings ($T_A=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20 μs)	Ppk	300	W
Peak Pulse Current (8/20 μs)	I _{PP}	12	A
ESD per IEC 61000-4-2 (Air)	VESD	± 30	kV
ESD per IEC 61000-4-2 (Contact)		± 30	
Operating Temperature Range	T _J	-55 to +125	$^{\circ}\text{C}$
Storage Temperature Range	T _{stg}	-55 to +150	$^{\circ}\text{C}$

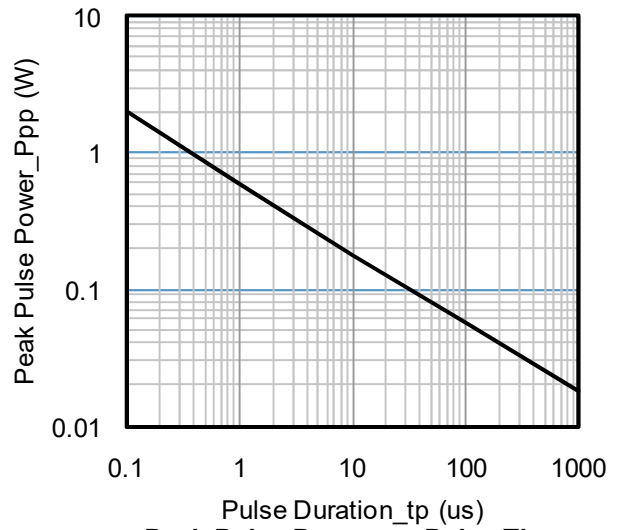
Electrical Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise specified)

Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	V _{RWM}			5	V	Any I/O pin to ground
Breakdown Voltage	V _{BR}	6			V	I _T = 1mA, any I/O pin to ground
Reverse Leakage Current	I _R			0.5	μA	V _{RWM} = 5V, any I/O pin to ground
Clamping Voltage	V _C		8.5	12.5	V	I _{PP} = 1A (8 x 20 μs pulse), any I/O pin to ground
Clamping Voltage	V _C		15.0	25	V	I _{PP} = 12A (8 x 20 μs pulse), any I/O pin to ground
Forward Voltage	V _F		1.0	1.2	V	I _F = 10mA, between ground to I/O pins and between I/O pins to V _{CC}
Junction Capacitance	C _J		1.5	2.5	pF	V _R = 0V, f = 1MHz, between I/O pins
Junction Capacitance	C _J		3	5	pF	V _R = 0V, f = 1MHz, any I/O pin to ground

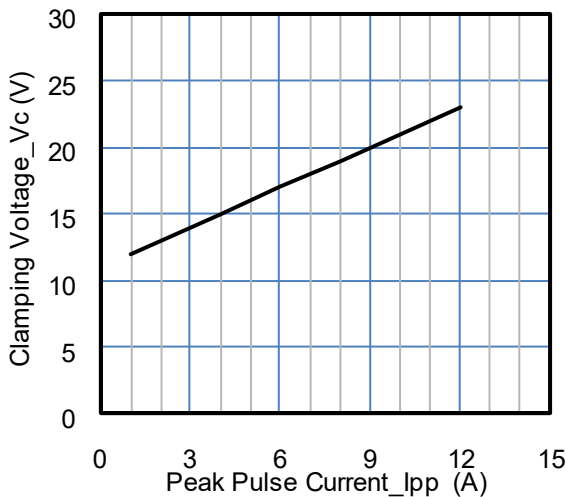
Typical Performance Characteristics (TA=25°C unless otherwise Specified)



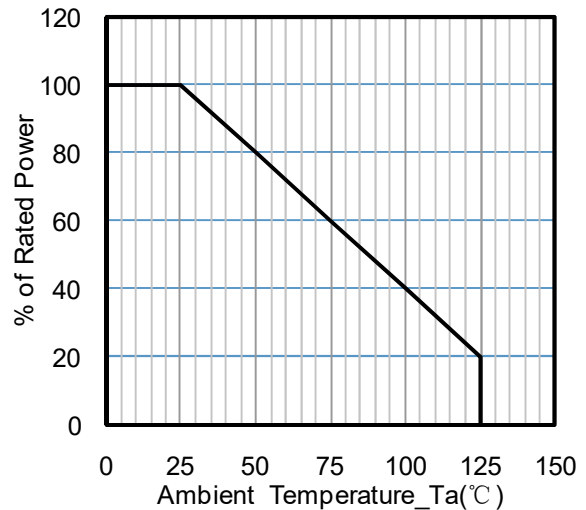
Junction Capacitance vs. Reverse Voltage



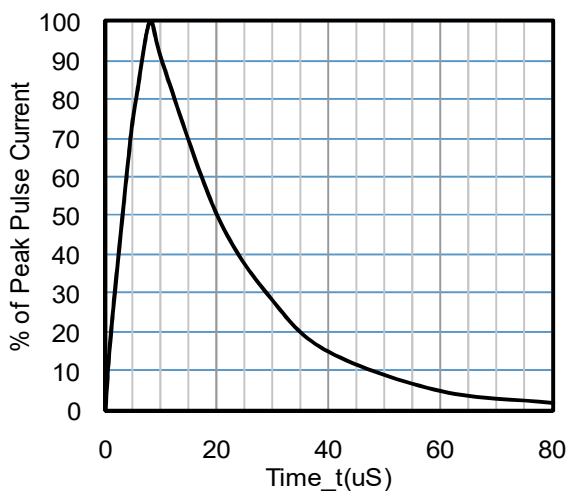
Peak Pulse Power vs. Pulse Time



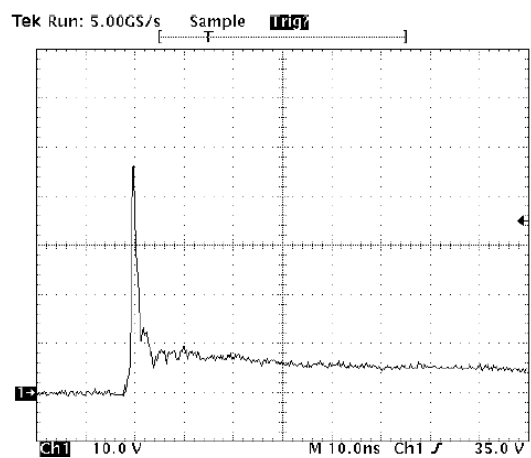
Clamping Voltage vs. Peak Pulse Current



Power Derating Curve



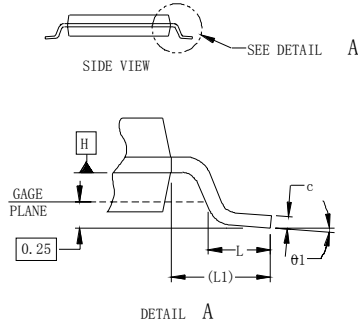
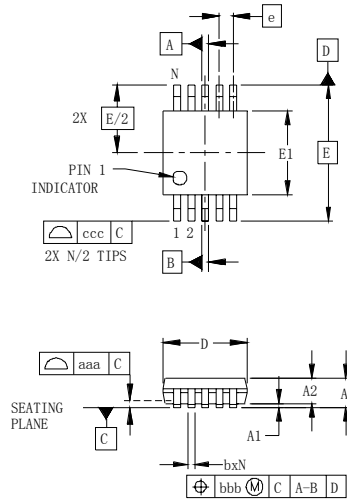
8 X 20uS Pulse Waveform



ESD Clamping Voltage

8 kV Contact per IEC61000-4-2

MSOP-10 Package Outline Drawing

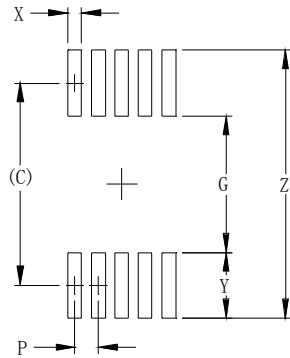


DIM	DIMENSIONS					
	INCHES			MILLIMETERS		
	MIN	NOM	MAX	MIN	NOM	MAX
A	-	-	.043	-	-	1.10
A1	.000	-	.006	0.00	-	0.15
A2	.030	-	.037	0.75	-	0.95
b	.007	-	.011	0.17	-	0.27
c	.003	-	.009	0.08	-	0.23
D	.114	.118	.122	2.90	3.00	3.10
E1	.114	.118	.122	2.90	3.00	3.10
E				.193 BSC 4.90 BSC		
e				.020 BSC 0.50 BSC		
L	.016	.024	.032	0.40	0.60	0.80
L1				(0.037) (.95)		
N	10			10		
theta1	0°	-	8°	0°	-	8°
aaa	.004			0.10		
bbb	.003			0.08		
ccc	.010			0.25		

NOTES:

1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
2. DATUMS **-A-** AND **-B-** TO BE DETERMINED AT DATUM PLANE **-H-**
3. DIMENSIONS "E1" AND "D" DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
4. REFERENCE JEDEC STD MO-187, VARIATION BA.

Suggested Land Pattern



DIM	DIMENSIONS	
	INCHES	MILLIMETERS
C	(.161)	(4.10)
G	.098	2.50
P	.020	0.50
X	.011	0.30
Y	.063	1.60
Z	.224	5.70

NOTES:

1. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

Contact Information

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